Preferred Device

Dual Switching Diode

Features

• Pb-Free Packages are Available

MAXIMUM RATINGS $(T_A = 25^{\circ}C)$

Rating	Symbol	Max	Unit
Continuous Reverse Voltage	V _R	75	V
Recurrent Peak Forward Current	lF	200	mA
Peak Forward Surge Current Pulse Width = 10 μs	I _{FM(surge)}	500	mA

THERMAL CHARACTERISTICS

Characteristic (One Junction Heated)	Symbol	Max	Unit
Total Device Dissipation $T_A = 25$ °C Derate above 25°C	P _D	357 (Note 1) 2.9 (Note 1)	mW mW/°C
Thermal Resistance Junction-to-Ambient	$R_{\theta JA}$	350 (Note 1)	°C/W
Characteristic			
(Both Junctions Heated)	Symbol	Max	Unit
(Both Junctions Heated) Total Device Dissipation $T_A = 25^{\circ}C$ Derate above 25°C	Symbol P _D	500 (Note 1) 4.0 (Note 1)	mW mW/°C
Total Device Dissipation $T_A = 25^{\circ}C$	-	500 (Note 1) 4.0	mW

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

1. FR-4 @ Minimum Pad



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SOT-563 CASE 463A PLASTIC

MARKING DIAGRAM



A6 = Specific Device Code

M = Date Code

■ = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping [†]
BAS16DXV6T1	SOT-563	4 mm pitch 4000/Tape & Reel
BAS16DXV6T1G	SOT-563 (Pb-Free)	4 mm pitch 4000/Tape & Reel
BAS16DXV6T5	SOT-563	2 mm pitch 8000/Tape & Reel
BAS16DXV6T5G	SOT-563 (Pb-Free)	2 mm pitch 8000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

Preferred devices are recommended choices for future use and best overall value.

ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
Forward Voltage $(I_F = 1.0 \text{ mA})$ $(I_F = 10 \text{ mA})$ $(I_F = 50 \text{ mA})$ $(I_F = 150 \text{ mA})$	V _F	- - - -	715 855 1000 1250	mV
Reverse Current $(V_R = 75 \text{ V})$ $(V_R = 75 \text{ V}, T_J = 150^{\circ}\text{C})$ $(V_R = 25 \text{ V}, T_J = 150^{\circ}\text{C})$	I _R	- - -	1.0 50 30	μΑ
Capacitance (V _R = 0, f = 1.0 MHz)	C _D	-	2.0	pF
Reverse Recovery Time (I _F = I _R = 10 mA, R _L = 50 Ω) (Figure 1)	t _{rr}	-	6.0	ns
Stored Charge (I _F = 10 mA to V_R = 6.0 V, R_L = 500 Ω) (Figure 2)	QS	-	45	PC
Forward Recovery Voltage (I _F = 10 mA, t _r = 20 ns) (Figure 3)	V _{FR}	-	1.75	V

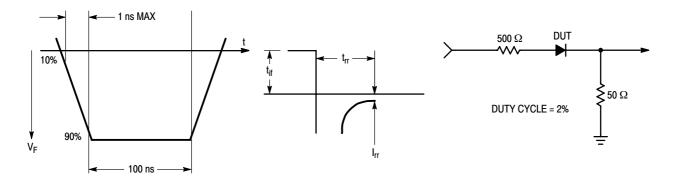


Figure 1. Reverse Recovery Time Equivalent Test Circuit

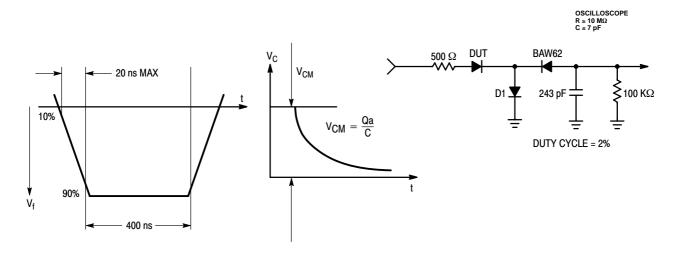


Figure 2. Stored Charge Equivalent Test Circuit

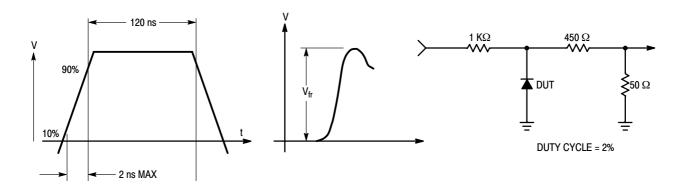
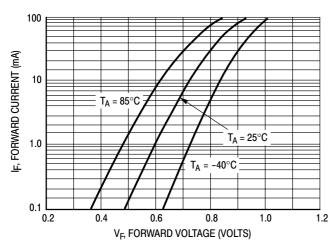


Figure 3. Forward Recovery Voltage Equivalent Test Circuit



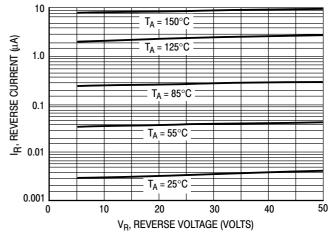


Figure 4. Forward Voltage

Figure 5. Leakage Current

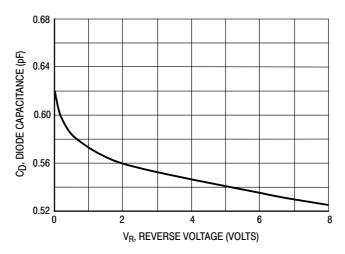


Figure 6. Capacitance

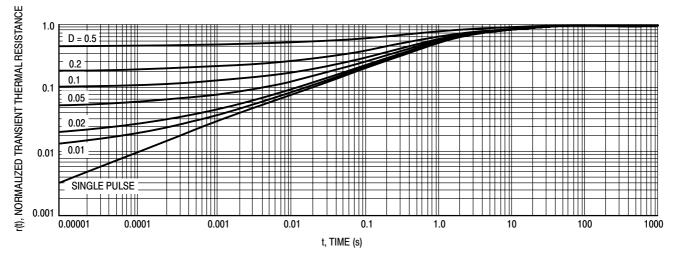
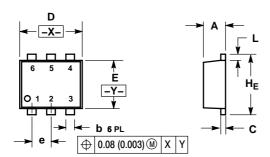


Figure 7. Normalized Thermal Response

PACKAGE DIMENSIONS

SOT-563, 6 LEAD CASE 463A-01 ISSUE F

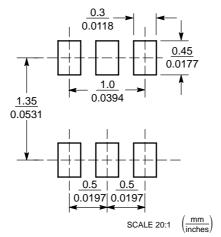


- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 CONTROLLING DIMENSION: MILLIMETERS
 MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

	MIL	MILLIMETERS			INCHES		
DIN	/ MIN	NOM	MAX	MIN	NOM	MAX	
Α	0.50	0.55	0.60	0.020	0.021	0.023	
b	0.17	0.22	0.27	0.007	0.009	0.011	
С	0.08	0.12	0.18	0.003	0.005	0.007	
D	1.50	1.60	1.70	0.059	0.062	0.066	
E	1.10	1.20	1.30	0.043	0.047	0.051	
е		0.5 BSC			0.02 BS0		
L	0.10	0.20	0.30	0.004	0.008	0.012	
He	1.50	1.60	1.70	0.059	0.062	0.066	

STYLE 10: PIN 1. CATHODE 1 2. N/C 3. CATHODE 2 4. ANODE 2 5. N/C 6. ANODE 1

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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